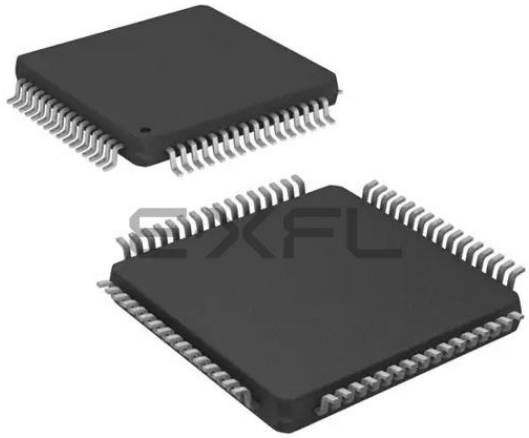
Microchip Technology - DSPIC33EP256MC506-H/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc506-h-pt

Referenced Sources

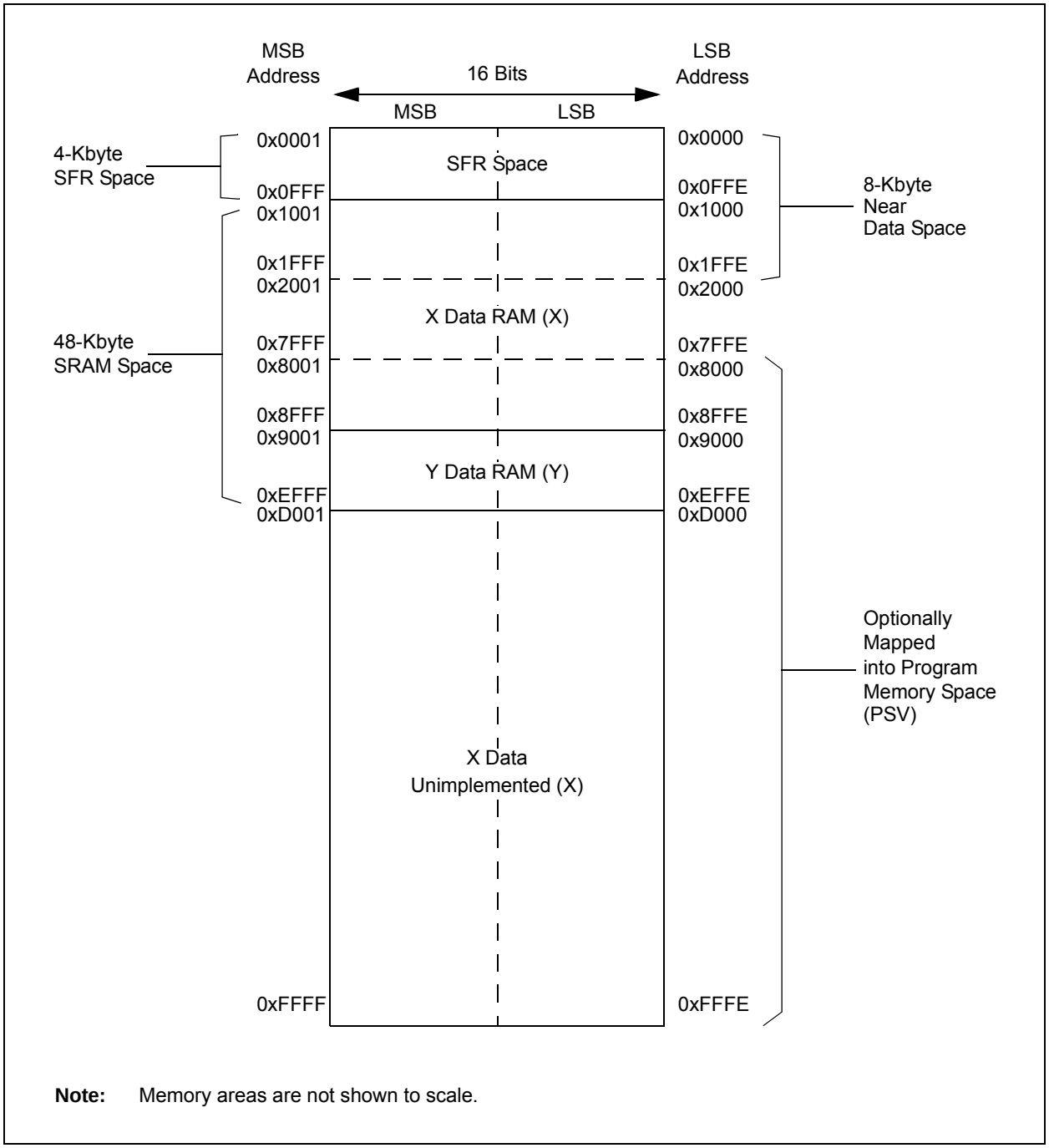
This device data sheet is based on the following individual chapters of the *"dsPIC33/PIC24 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the dsPIC33EP64MC506 product page of the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features and other documentation, the resulting page provides links to the related family reference manual sections.

- **"Introduction"** (DS70573)
- **"CPU"** (DS70359)
- **"Data Memory"** (DS70595)
- **"Program Memory"** (DS70613)
- **"Flash Programming"** (DS70609)
- **"Interrupts"** (DS70600)
- **"Oscillator"** (DS70580)
- **"Reset"** (DS70602)
- **"Watchdog Timer and Power-Saving Modes"** (DS70615)
- **"I/O Ports"** (DS70598)
- **"Timers"** (DS70362)
- **"Input Capture"** (DS70352)
- **"Output Compare"** (DS70358)
- **"High-Speed PWM"** (DS70645)
- **"Quadrature Encoder Interface (QEI)"** (DS70601)
- **"Analog-to-Digital Converter (ADC)"** (DS70621)
- **"UART"** (DS70582)
- **"Serial Peripheral Interface (SPI)"** (DS70569)
- **"Inter-Integrated Circuit (I^2C™)"** (DS70330)
- **"Enhanced Controller Area Network (ECAN™)"** (DS70353)
- **"Direct Memory Access (DMA)"** (DS70348)
- **"CodeGuard™ Security"** (DS70634)
- **"Programming and Diagnostics"** (DS70608)
- **"Op Amp/Comparator"** (DS70357)
- **"Programmable Cyclic Redundancy Check (CRC)"** (DS70346)
- **"Device Configuration"** (DS70618)
- **"Peripheral Trigger Generator (PTG)"** (DS70669)
- **"Charge Time Measurement Unit (CTMU)"** (DS70661)

FIGURE 4-11: DATA MEMORY MAP FOR dsPIC33EP512MC20X/50X AND dsPIC33EP512GP50X DEVICES



Note: Memory areas are not shown to scale.

4.4 Special Function Register Maps

TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000	W0 (WREG)																xxxx
W1	0002	W1																xxxx
W2	0004	W2																xxxx
W3	0006	W3																xxxx
W4	0008	W4																xxxx
W5	000A	W5																xxxx
W6	000C	W6																xxxx
W7	000E	W7																xxxx
W8	0010	W8																xxxx
W9	0012	W9																xxxx
W10	0014	W10																xxxx
W11	0016	W11																xxxx
W12	0018	W12																xxxx
W13	001A	W13																xxxx
W14	001C	W14																xxxx
W15	001E	W15																xxxx
SPLIM	0020	SPLIM																0000
ACCAL	0022	ACCAL																0000
ACCAH	0024	ACCAH																0000
ACCAU	0026	Sign Extension of ACCA<39>								ACCAU								0000
ACCBL	0028	ACCBL																0000
ACCBH	002A	ACCBH																0000
ACCBU	002C	Sign Extension of ACCB<39>								ACCBU								0000
PCL	002E	PCL<15:0>															—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>									0001
RCOUNT	0036	RCOUNT<15:0>																0000
DCOUNT	0038	DCOUNT<15:0>																0000
DOSTARTL	003A	DOSTARTL<15:1>															—	0000
DOSTARTH	003C	—	—	—	—	—	—	—	—	—	—	DOSTARTH<5:0>						0000
DOENDL	003E	DOENDL<15:1>															—	0000
DOENDH	0040	—	—	—	—	—	—	—	—	—	—	DOENDH<5:0>						0000

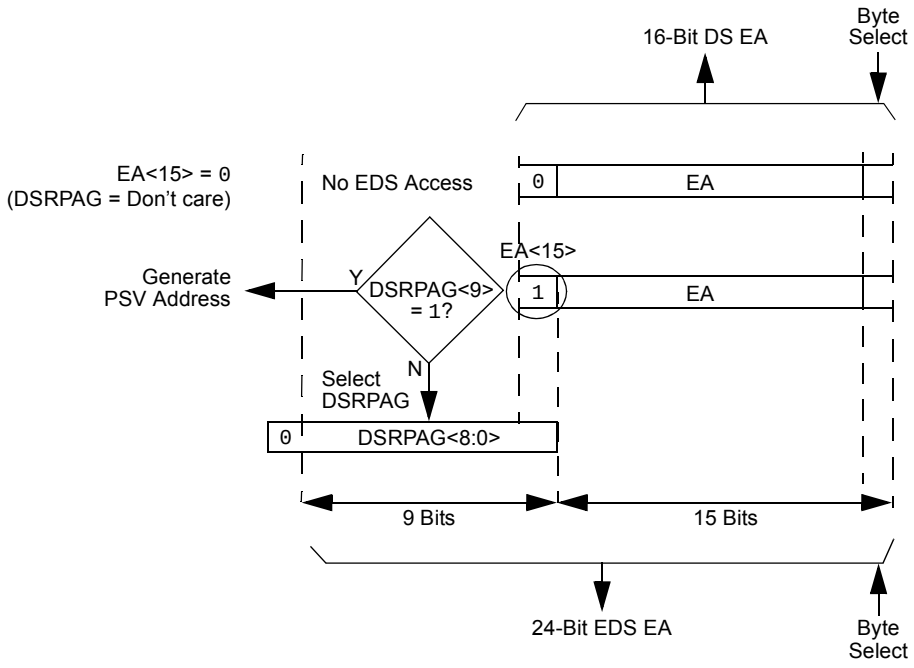
Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS) address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = 0 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = 1, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions, which apply to dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and the DSP accumulator class of instructions, which apply to the dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices, provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note:	For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-Bit Literal
- 16-Bit Literal

Note:	Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.5.4 MAC INSTRUCTIONS (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X DEVICES ONLY)

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the Data Pointers through register indirect tables.

The Two-Source Operand Prefetch registers must be members of the set: {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The Effective Addresses generated (before and after modification) must therefore, be valid addresses within X Data Space for W8 and W9, and Y Data Space for W10 and W11.

Note:	Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ULNK, the source of an operand or result is implied by the opcode itself. Certain operations, such as a NOP, do not have any operands.

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
GIE	DISI	SWTRAP	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **GIE:** Global Interrupt Enable bit
1 = Interrupts and associated IE bits are enabled
0 = Interrupts are disabled, but traps are still enabled

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13 **SWTRAP:** Software Trap Status bit
1 = Software trap is enabled
0 = Software trap is disabled

bit 12-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than VDD by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum VIH specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum VIH specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```

16.1.2 WRITE-PROTECTED REGISTERS

On dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices, write protection is implemented for the IOCONx and FCLCONx registers. The write protection feature prevents any inadvertent writes to these registers. This protection feature can be controlled by the PWMLOCK Configuration bit (FOSCSEL<6>). The default state of the write protection feature is enabled (PWMLOCK = 1). The write protection feature can be disabled by configuring, PWMLOCK = 0.

To gain write access to these locked registers, the user application must write two consecutive values of (0xABCD and 0x4321) to the PWMKEY register to perform the unlock operation. The write access to the IOCONx or FCLCONx registers must be the next SFR access following the unlock process. There can be no other SFR accesses during the unlock process and subsequent write access. To write to both the IOCONx and FCLCONx registers requires two unlock operations.

The correct unlocking sequence is described in Example 16-1.

EXAMPLE 16-1: PWMx WRITE-PROTECTED REGISTER UNLOCK SEQUENCE

```
; FLT32 pin must be pulled low externally in order to clear and disable the fault
; Writing to FCLCON1 register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0x0000,w0        ; Load desired value of FCLCON1 register in w0
mov w10, PWMKEY       ; Write first unlock key to PWMKEY register
mov w11, PWMKEY       ; Write second unlock key to PWMKEY register
mov w0,FCLCON1        ; Write desired value to FCLCON1 register

; Set PWM ownership and polarity using the IOCON1 register
; Writing to IOCON1 register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0xF000,w0        ; Load desired value of IOCON1 register in w0
mov w10, PWMKEY       ; Write first unlock key to PWMKEY register
mov w11, PWMKEY       ; Write second unlock key to PWMKEY register
mov w0,IOCON1         ; Write desired value to IOCON1 register
```

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit
When IDE = 0:
1 = Message will request remote transmission
0 = Normal message
When IDE = 1:
The SRR bit must be set to '1'.

bit 0 **IDE:** Extended Identifier bit
1 = Message will transmit Extended Identifier
0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

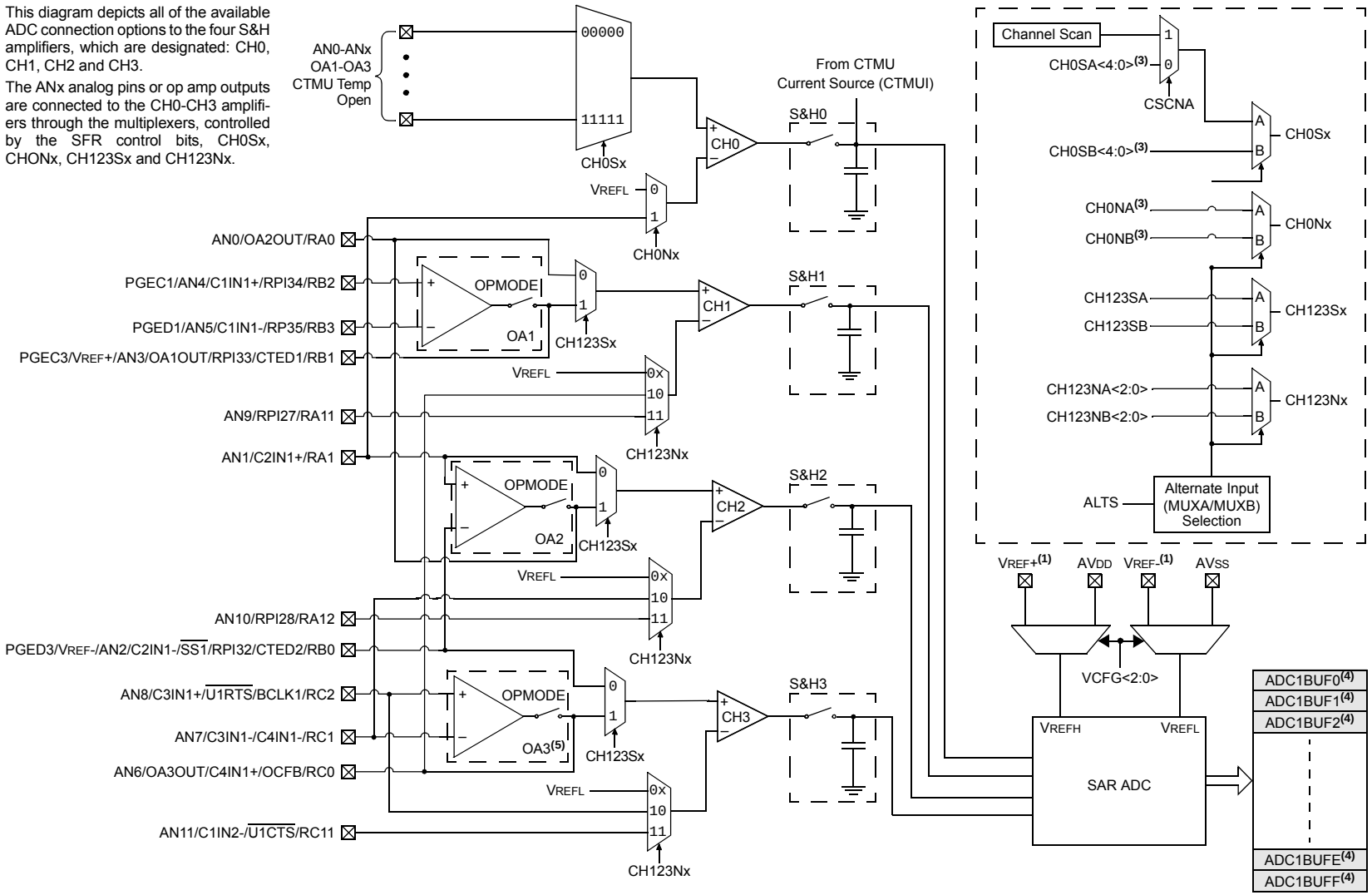
bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **EID<17:6>:** Extended Identifier bits

FIGURE 23-1: ADC MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CHONx, CH123Sx and CH123Nx.



Note 1: VREF+, VREF- inputs can be multiplexed with other analog inputs.
2: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
3: These bits can be updated with Step commands from the PTG module. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
4: When ADDMAEN (AD1CON4<8>) = 1, enabling DMA, only ADC1BUF0 is used.
5: OA3 is not available for 28-pin devices.

24.2 PTG Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

24.2.1 KEY RESOURCES

- **"Peripheral Trigger Generator"** (DS70669) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

25.0 OP AMP/COMPARATOR MODULE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Op Amp/Comparator"** (DS70357) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain up to four comparators, which can be configured in various ways. Comparators, CMP1, CMP2 and CMP3, also have the option to be configured as op amps, with the output being brought to an external pin for gain/filtering connections. As shown in Figure 25-1, individual comparator options are specified by the comparator module's Special Function Register (SFR) control bits.

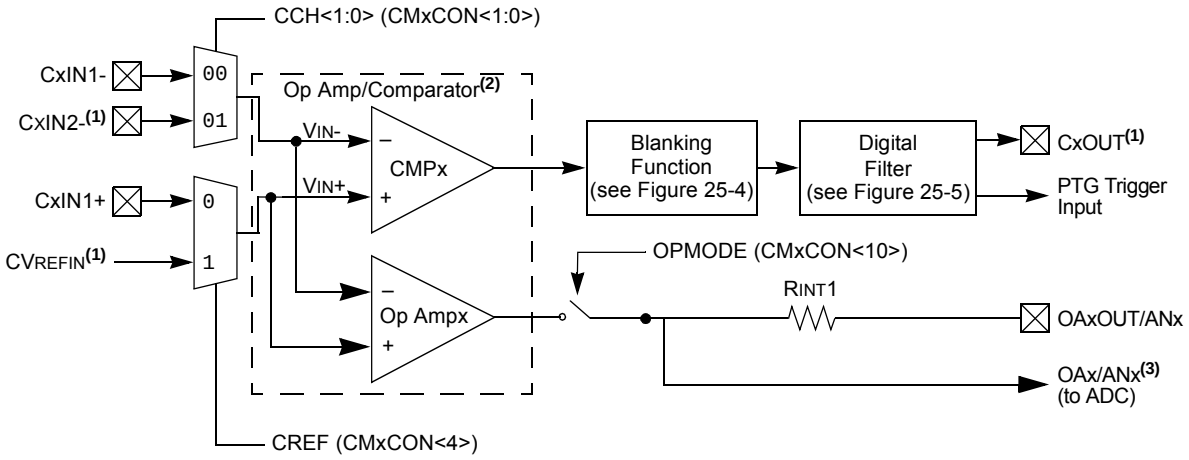
Note: Op Amp/Comparator 3 is not available on the dsPIC33EPXXXGP502/MC502/MC202 and PIC24EP256GP/MC202 (28-pin) devices.

These options allow users to:

- Select the edge for trigger and interrupt generation
- Configure the comparator voltage reference
- Configure output blanking and masking
- Configure as a comparator or op amp (CMP1, CMP2 and CMP3 only)

Note: Not all op amp/comparator input/output connections are available on all devices. See the **"Pin Diagrams"** section for available connections.

FIGURE 25-1: OP AMP/COMPARATOR x MODULE BLOCK DIAGRAM (MODULES 1, 2 AND 3)



Note 1: This input/output is not available as a selection when configured as an op amp (OPMODE (CMxCON<10>) = 1).

2: This module can be configured either as an op amp or a comparator using the OPMODE bit.

3: When configured as an op amp (OPMODE = 1), the ADC samples the op amp output; otherwise, the ADC samples the ANx pin.

REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER (CONTINUED)

bit 1 **C2OUT:** Comparator 2 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 0 **C1OUT:** Comparator 1 Output Status bit(2)

When CPOL = 0:
1 = VIN+ > VIN-
0 = VIN+ < VIN-

When CPOL = 1:
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.

2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

TABLE 28-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
1	ADD	ADD	Acc(1)	Add Accumulators	1	1	OA,OB,SA,SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA,SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (4)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (4)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (4)	None
		BRA	GT,Expr	Branch if greater than	1	1 (4)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (4)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (4)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (4)	None
		BRA	LT,Expr	Branch if less than	1	1 (4)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (4)	None
		BRA	N,Expr	Branch if Negative	1	1 (4)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (4)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (4)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (4)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (4)	None
		BRA	OA,Expr(1)	Branch if Accumulator A overflow	1	1 (4)	None
		BRA	OB,Expr(1)	Branch if Accumulator B overflow	1	1 (4)	None
		BRA	OV,Expr(1)	Branch if Overflow	1	1 (4)	None
		BRA	SA,Expr(1)	Branch if Accumulator A saturated	1	1 (4)	None
		BRA	SB,Expr(1)	Branch if Accumulator B saturated	1	1 (4)	None
		BRA	Expr	Branch Unconditionally	1	4	None
		BRA	Z,Expr	Branch if Zero	1	1 (4)	None
		BRA	Wn	Computed Branch	1	4	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None
8	BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
		BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

29.11 Demonstration/Development Boards, Evaluation Kits and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to V_{SS}(3) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$(3) ..... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when $V_{DD} < 3.0V$(3) ..... -0.3V to +3.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin(2) ..... 300 mA
Maximum current sunk/sourced by any 4x I/O pin ..... 15 mA
Maximum current sunk/sourced by any 8x I/O pin ..... 25 mA
Maximum current sunk by all ports(2,4) ..... 200 mA

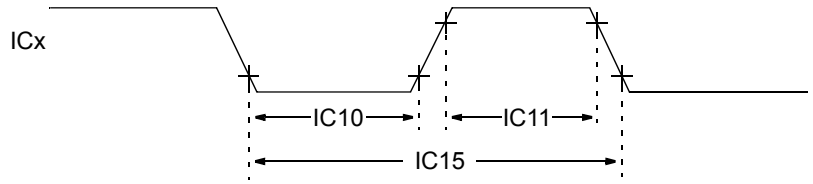
Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

4: Exceptions are: dsPIC33EPXXXGP502, dsPIC33EPXXXMC202/502 and PIC24EPXXXGP/MC202 devices, which have a maximum sink/source capability of 130 mA.

FIGURE 30-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-26: INPUT CAPTURE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TccL	ICx Input Low Time	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	N = prescale value (1, 4, 16)
IC11	TccH	ICx Input High Time	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	ns	Must also meet Parameter IC15	
IC15	TccP	ICx Input Period	Greater of 25 + 50 or (1 TCY/N) + 50	—	ns		

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-57: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 3.0	—	Lesser of: VDD + 0.3 or 3.6	V	
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	VREFH = VREF+ VREFL = VREF- **(Note 1)**
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	**(Note 1)**
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	— —	— —	10 600	μA μA	ADC off ADC on
AD09	IAD	Operating Current[2]	—	5	—	mA	ADC operating in 10-bit mode **(Note 1)**
			—	2	—	mA	ADC operating in 12-bit mode **(Note 1)**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample-and-Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	200	Ω	Impedance to achieve maximum performance of ADC

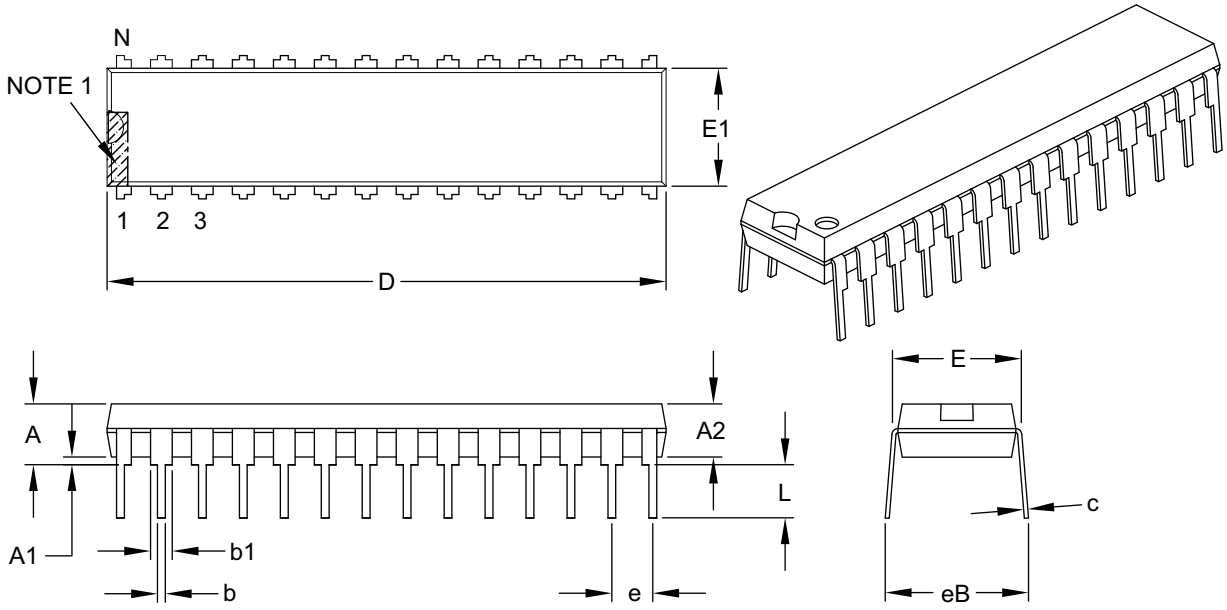
Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics" (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).